

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT7440637

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHENG-FAN YANG	07/06/2022
CHIH-CHIANG HUNG	06/30/2022
YUAN-HUNG LIN	07/06/2022
SHIH-HSUAN HSU	07/06/2022
IGOR ELKANOVICH	06/30/2022
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17863408
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	121997-US-PA
NAME OF SUBMITTER:	JAI-WEI CHEN

SIGNATURE:	/Jai-Wei Chen/
DATE SIGNED:	07/20/2022
Total Attachments: 4 source=121997US_DeclAssgn#page1.tif source=121997US_DeclAssgn#page2.tif source=121997US_DeclAssgn#page3.tif source=121997US_DeclAssgn#page4.tif	

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

☒ Declaration Submitted With Initial Filing

OR

☐ Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)

(Title of the Invention)

COMMUNICATION INTERFACE STRUCTURE AND DIE-TO-DIE PACKAGE

As a below named inventor (hereinafter designated as the undersigned), I hereby
declare that:

This declaration is directed to:

☒ The attached application,

OR

☐ United States Application Number or PCT International application number

_____ Filed on _____

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in
the application.

The undersigned hereby acknowledge that any willful false statement made in this
declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more
than five (5) years, or both.

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS, 1. Global Unichip Corporation
of No.10, Lixing 6th Rd., Science-Based Industrial Park, Hsinchu 30078,
Taiwan (R.O.C.)
, 2. Taiwan Semiconductor Manufacturing Company, Ltd.
of No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78,
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

2022-012US
121997-US-PA

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Sheng-Fan Yang Date: 2022.7.6

Legal Name of Sole or First Inventor: **Sheng-Fan Yang**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No.10, Lixing 6th Rd., Science-Based Industrial Park, Hsinchu 30078, Taiwan
(R.O.C.)

Signature: chih chiang hung Date: 2022.06.30

Legal Name of Additional Joint Inventor, if any: **Chih-Chiang Hung**

Residence: Hsinchu, Taiwan

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Signature: Yuan-Hung Lin Date: 2022.7.6

Legal Name of Additional Joint Inventor, if any: **Yuan-Hung Lin**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No.10, Lixing 6th Rd., Science-Based Industrial Park, Hsinchu 30078, Taiwan
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Signature: Shih-Hsuan Hsu Date: 2022.7.6

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(R.O.C.)

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature:  Date: 30/June/2022

Legal Name of Additional Joint Inventor, if any: Igor Elkanovich

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